Features

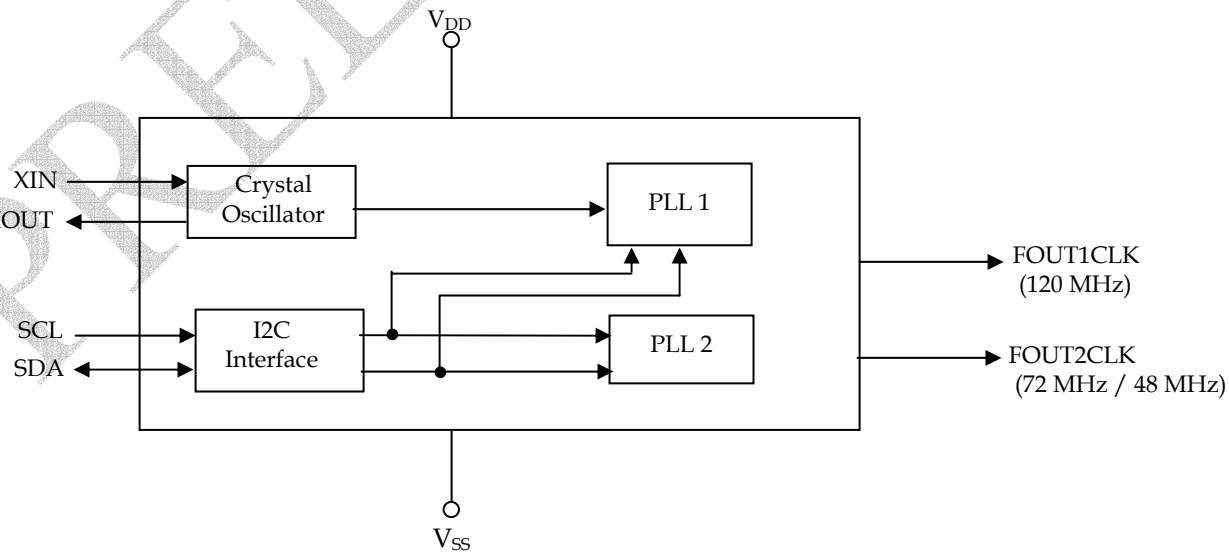
- Generates an EMI optimized clocking signal at output.
- Input frequency – 14.31818 MHz.
- Frequency outputs:
  - 120 MHz (modulated) - default.
  - 72 MHz (modulated) or 48 MHz (modulated) selectable via I2C
- ± 1% Centre spread.
- Modulation rate: 40 KHz.
- Byte Write via I2C
- Supply voltage range 3.3V (± 0.3V).
- Available in 8-pin SOIC package.
- Commercial and Industrial Temperature range.

Product Description

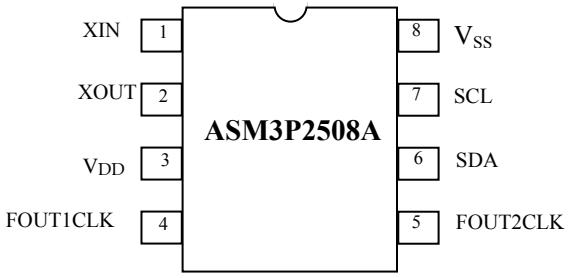
The ASM3P2508A is a versatile spread spectrum frequency modulator. The ASM3P2508A reduces electromagnetic interference (EMI) at the clock source. The ASM3P2508A allows significant system cost savings by reducing the number of circuit board layers and shielding that are required to pass EMI regulations. The ASM3P2508A modulates the output of PLL in order to spread the bandwidth of a synthesized clock, thereby decreasing the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most clock generators. Lowering EMI by increasing a signal's bandwidth is called spread spectrum clock generation.

The ASM3P2508A has a feature to power down the 72MHz / 48MHz output by writing data into specific registers in the device via I2C. By writing a '0' into bit 1 of Byte 0, the PLL block generating 72 MHz / 48MHz can be powered down. Writing '0' into bit '7' of Byte 1 selects an output of 72 MHz on FOUT2CLK while a '1' at the same location selects a 48 MHz clock output. However, the I2C block, crystal oscillator, and the PLL block generating 120MHz would be always running.

Block Diagram



Pin Configuration



Pin Description

Pin Name	Type	Description
XIN	I	Connection to crystal
XOUT	O	Connection to crystal
V_{DD}	P	Power supply for the analog and digital blocks
FOUT1CLK	O	Clock output-1 (120 MHz) - default
FOUT2CLK	O	Clock output-2 (72 MHz / 48 MHz)
SDA	I/O	I2C Data
SCL	I	I2C Clock
V_{SS}	P	Ground to entire chip

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
V_{DD}	Supply voltage, DC	(V_{SS} – 0.5) to 7	V
V_I	Input voltage, DC	(V_{SS}-0.5) to (V_{DD}+0.5)	V
V_O	Output voltage, DC	(V_{SS}-0.5) to (V_{DD} + 0.5)	V
I_{IK}	Input clamp current (V_I<0 or V_I>V_{DD})	-50 to +50	mA
I_{OK}	Output clamp current (V_I<0 or V_I>V_{DD})	-50 to +50	mA
T_S	Storage temperature	-65 to +125	°C
T_A	Ambient temperature range, under bias	-55 to 125	°C
T_J	Junction temperature	150	°C
	Lead temperature (soldering 10 sec)	260	°C
	Input static discharge voltage protection (MIL – STD 883E, Method 3015.7)	2	kV
Note: These are stress ratings only and functional operation is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.			

Operating Conditions

Parameter	Symbol	Condition / Description	Min	Typ	Max	Unit
Supply Voltage	V_{DD}	3.3V ± 10%	3	3.3	3.6	V
Ambient Operating Temperature Range	T_A		-10		+70	°C
Crystal Resonator Frequency	F_{XIN}		14.31818			MHz
Serial Data Transfer Rate		Standard Mode	10		100	kb/s
Output Driver Load Capacitance	C_L				15	pF

DC Electrical Characteristics

Parameter	Symbol	Conditions / Description	Min	Typ	Max	Unit
Overall						
Supply Current, Dynamic	I_{DD}	V_{DD}=3.3V, F_{CLK}=14.31818MHz, C_L=15pF		43		mA
Supply Current, Static	I_{DDL}	V_{DD} = 3.3V, Software Power Down		tbd		mA
All input pins						
High-Level Input Voltage	V_{IH}	V_{DD}=3.3V	2.0		V_{DD}+0.3	V
Low-Level Input Voltage	V_{IL}	V_{DD}=3.3V	V_{SS}-0.3		0.8	V
High-Level Input Current	I_{IH}		-1		1	μA
Low-Level Input Current (pull-up)	I_{IL}		-20	-36	-80	μA
High-Level Output Source Current	I_{xOH}	V_{DD}=V(XIN) = 3.3V, V_O=0V	10	21	30	mA
Low-Level Output Source Current	I_{xOL}	V_{DD}=3.3V, V(XIN)=V_O=5.5V	-10	-21	-30	mA
Clock Outputs (FOUT1CLK, FOUT2CLK)						
High-Level Output Source Current	I_{OH}	V_O=2.4V		-20		mA
Low-Level Output Sink Current	I_{OL}	V_O=0.4V		23		mA
Output Impedance	Z_{OH}	V_O=0.5V_{DD}; output driving high		29		Ω
	Z_{OL}	Vo=0.5V_{DD}; output driving low		27		

AC Electrical Characteristics

Parameter	Symbol	Conditions/ Description	Min	Typ	Max	Unit
Rise Time	t_r	V_O = 0.3V to 3.0V; CL = 15pF		2.1		ns
Fall Time	t_f	V_O = 3.0V to 0.3V; CL = 15pF		1.9		ns
Clock Duty Cycle		Ratio of pulse width (as measured from rising edge to next falling edge at 2.5V) to one clock period	45		55	%
Jitter, Long Term	$Tj_{(LT)}$	On rising edges 500 uS apart at 2.5 V relative to an ideal clock, PLL B inactive *		45		pS
		On rising edges 500 uS apart at 2.5 V relative to an ideal clock, PLL B active *		165		
Jitter, peak to peak	$Tj_{(\Delta T)}$	From rising edge to next rising edge at 2.5 V, PLL B inactive *		110		pS
		From rising edge to next rising edge at 2.5 V, PLL B active *		390		
Clock Stabilization Time	t_{STB}	Output active from power up, RUN Mode via Software Power Down		125		µs
* CL = 15 pF, Fxin = 14.31818 MHz, Fout = 50 MHz						

Crystal Specifications

Fundamental AT cut parallel resonant crystal	
Nominal Frequency	14.31818 MHz
Frequency Tolerance	+/- 50 ppm or better at 25°C
Operating temperature range	-20°C to +85°C
Storage Temperature	-40°C to +85°C
Load Capacitance	18pF
Shunt capacitance	7 pF maximum
ESR	25 Ω

I2C Serial Interface Information

The information in this section assumes familiarity with I2C programming.

How to program ASM3P2508A through I2C:

- Master (host) sends a start bit.
- Master (host) sends the write address D4 (H).
- ASM3P2508A device will acknowledge.
- Master (host) sends the beginning byte location (N = 0, 1).
- ASM3P2508A device will acknowledge.
- Master (host) sends a byte count (X = 1,2)
- ASM3P2508A device will acknowledge.
- Master (host) starts sending byte N through byte (N+X – 1)
- ASM3P2508A device will acknowledge each byte one at a time.
- Master (host) sends a Stop bit.

Controller (Host)	ASM3P2508A (slave/receiver)
Start Bit	
Slave Address D4(H)	
	ACK
Beginning byte location (=N)	
	ACK
Byte count (=X)	
	ACK
Beginning byte (Byte N)	
	ACK
Next Byte (Byte N+1)	
	ACK

Last Byte (Byte N+X-1)	
	ACK
Stop Bit	

How to Read from ASM3P2508A through I2C:

- Master (host) will send start bit.
- Master (host) sends the write address D4 (H).
- ASM3P2508A device will acknowledge.
- Master (host) sends the beginning byte location (N = 0, 1).
- ASM3P2508A device will acknowledge.
- Master (host) will send a separate start bit.
- Master (host) sends the read address D5 (H).
- ASM3P2508A device will acknowledge.
- ASM3P2508A device will send the byte count (X = 1, 2).
- Master (host) acknowledges.
- ASM3P2508A device sends byte N through byte (N+X – 1).
- Master (host) will need to acknowledge each byte.
- Master (host) will send a stop bit.

Controller (Host)	ASM3P2508A (slave/receiver)
Start Bit	
Slave Address D4(H)	
	ACK
Beginning Byte = N	
	ACK
Repeat start	
Slave address D5(H)	
	ACK
	Byte Count (= X)
ACK	
	Beginning byte N
ACK	
	Next Byte N+1
ACK	

	Last Byte (Byte N+X-1)
Not Acknowledge	
Stop Bit	

An example of a Byte Write via I2C to partially 'power down' the device:

ASM3P2508A can be partially 'powered down' using bit 1 of Byte 0. The organization of the register bits for Byte '0' is given with default values below:

Bit							
7	6	5	4	3	2	1	0
Resv	Resv	Resv	Resv	Resv	Resv	PLL2 Enable	PLL1 Enable
0	1	0	1	0	1	1	1

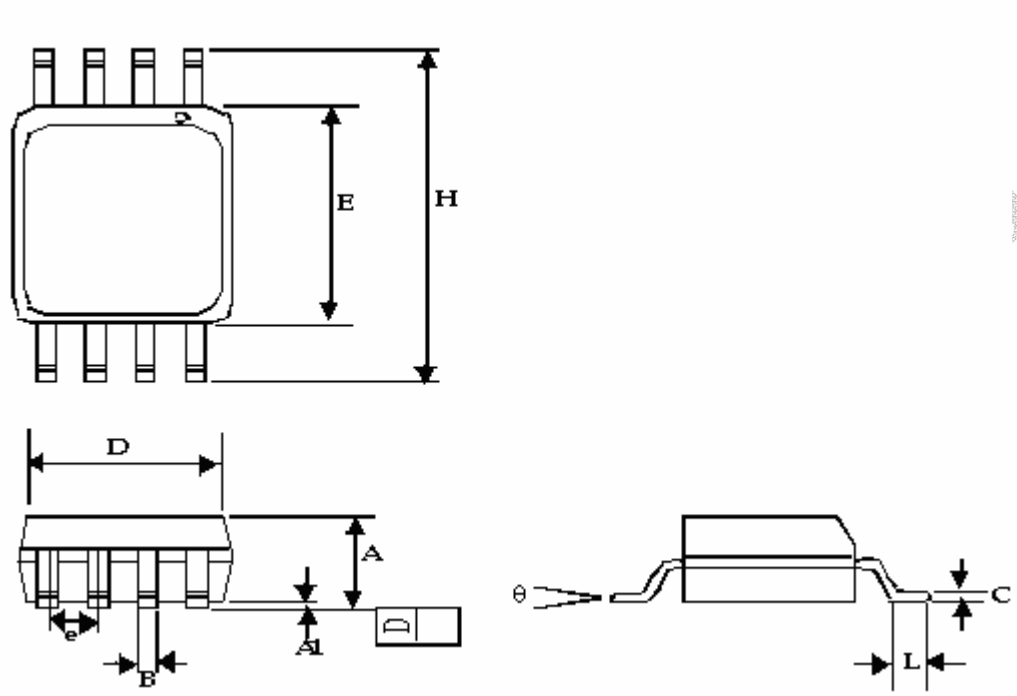
The function of partial power down of the device is of interest to us - that is bit 1 of Byte 0. In the default mode this bit is logic '1'. As such, the Byte 0 default value is 57 (H). To put ASM3P2508A in 'power down' mode, the bit 1of Byte 0 is to be changed to logic '0'. Hence writing a 55 (H) via I2C into Byte 0 would put the device in partial 'power down' mode where the PLL block generating 72 MHz / 48 MHz would be powered down while I2C block, crystal oscillator, and the PLL block generating 120 MHz would still be active. The organization of the register bits is as below:

Bit							
7	6	5	4	3	2	1	0
Resv	Resv	Resv	Resv	Resv	Resv	PLL2 Enable	PLL1 Enable
0	1	0	1	0	1	0	1

	Byte 0	Byte 1	FOUT1CLK (MHz)	FOUT2CLK(MHz)
Power up default			120	72
48_MHz Mode			120	48
Power down PLL with 72MHz			120	
Power down PLL with 48MHz			120	

Package Information

8-Pin SOIC



Symbol	Dimensions in inches		Dimensions in millimeters	
	Min	Max	Min	Max
A	0.053	0.069	1.35	1.75
A1	0.004	0.010	0.10	0.25
B	0.013	0.022	0.33	0.53
C	0.007	0.012	0.18	0.27
D	0.188	0.197	4.78	5.00
E	0.150	0.158	3.80	4.01
H	0.228	0.244	5.80	6.20
e	0.050 BSC		1.27 BSC	
L	0.016	0.035	0.40	0.89
θ	0°	8°	0°	8°

Ordering Codes

Part number	Package Configuration	Package Type
ASM3P2508A-08-ST	8-PIN SOIC	TUBE
ASM3P2508A-08-SR	8-PIN SOIC	TAPE AND REEL
ASM3I2508A-08-ST	8-PIN SOIC	TUBE
ASM3I2508A-08-SR	8-PIN SOIC	TAPE AND REEL

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Preliminary Information
Part Number: ASM3P2508A
Document Version: v1.1

Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to Dan Hariton / Alliance Semiconductor, dated 11-11-2003

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